SLLS101D - JULY 1985 - REVISED APRIL 2003

- Bidirectional Transceivers
- Meet or Exceed the Requirements of ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Driver and Receiver Outputs
- Individual Driver and Receiver Enables
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capability . . . ±60 mA Max
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operate From Single 5-V Supply

#### 

#### description/ordering information

The SN65176B and SN75176B differential bus transceivers are integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27.

The SN65176B and SN75176B combine a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or  $V_{CC} = 0$ . These ports feature wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

#### ORDERING INFORMATION

TA	PACKAGE†		PACKAGE <sup>†</sup> ORDERABLE PART NUMBER	
	PDIP (P)	Tube of 50	SN75176BP	SN75176BP
0°C to 70°C	COIC (D)	Tube of 75	SN75176BD	75176B
0°C to 70°C	SOIC (D)	Reel of 2500	SN75176BDR	751705
	SOP (PS)	Reel of 2000	SN75176BPSR	A176B
	PDIP (P)	Tube of 50	SN65176BP	SN65176BP
–40°C to 105°C	SOIC (D)	Tube of 75	SN65176BD	65176B
	SOIC (D)	Reel of 2500	SN65176BDR	001700

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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#### description/ordering information (continued)

The driver is designed for up to 60 mA of sink or source current. The driver features positive and negative current limiting and thermal shutdown for protection from line-fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The receiver features a minimum input impedance of 12 k $\Omega$ , an input sensitivity of  $\pm 200$  mV, and a typical input hysteresis of 50 mV.

The SN65176B and SN75176B can be used in transmission-line applications employing the SN75172 and SN75174 quadruple differential line drivers and SN75173 and SN75175 quadruple differential line receivers.

#### **Function Tables**

#### **DRIVER**

INPUT	ENABLE	OUTPUTS			
D	DE	Α	В		
Н	Н	Н	L		
L	Н	L	Н		
Х	L	Z	Z		

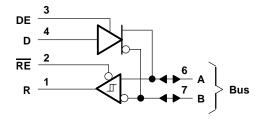
#### **RECEIVER**

DIFFERENTIAL INPUTS A-B	EN <u>AB</u> LE RE	OUTPUT R
V <sub>ID</sub> ≥ 0.2 V	L	Н
-0.2 V < V <sub>ID</sub> < 0.2 V	L	?
V <sub>ID</sub> ≤ -0.2 V	L	L
X	Н	Z
Open	L	?

H = high level, L = low level, ? = indeterminate,

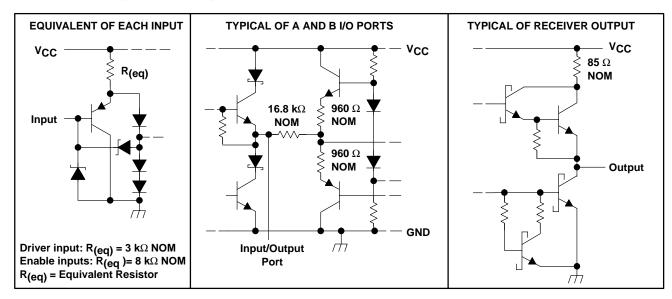
X = irrelevant, Z = high impedance (off)

#### logic diagram (positive logic)





#### schematics of inputs and outputs



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	
Enable input voltage, V <sub>1</sub>	
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): D package	
P package	85°C/W
PS packag	je 95°C/W
Operating virtual junction temperature, T <sub>J</sub>	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .	260°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

- 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



# SN65176B, SN75176B DIFFERENTIAL BUS TRANSCEIVERS

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#### recommended operating conditions

			MIN	TYP	MAX	UNIT
Vcc	Supply voltage		4.75	5	5.25	V
\/. or \/.o	V <sub>I</sub> or V <sub>IC</sub> Voltage at any bus terminal (separately or common mode)				12	V
ALOI AIC					-7	V
$V_{IH}$	High-level input voltage	D, DE, and RE	2			V
V <sub>IL</sub> Low-level input voltage D, DE, and RE					0.8	V
V <sub>ID</sub> Differential input voltage (see Note 4)					±12	V
lou	High-level output current	Driver			-60	mA
ЮН	High-level output current	Receiver			-400	μΑ
lo	Low-level output current	Driver			60	mA
IOL	Low-level output current	Receiver			8	ША
т.	Operating free-air temperature	SN65176B	-40		105	°C
T <sub>A</sub>	Operating nee-an temperature	SN75176B	0		70	C

NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal A, with respect to the inverting terminal B.

#### **DRIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
VIK	Input clamp voltage	I <sub>I</sub> = -18 mA				-1.5	V
٧o	Output voltage	I <sub>O</sub> = 0		0		6	V
V <sub>OD1</sub>	Differential output voltage	I <sub>O</sub> = 0		1.5	3.6	6	V
IV <sub>OD2</sub> I	Differential output voltage	R <sub>L</sub> = 100 Ω,	See Figure 1	1/2 V <sub>OD1</sub> or 2¶			V
		$R_L = 54 \Omega$ ,	See Figure 1	1.5	2.5	5	
V <sub>OD3</sub>	Differential output voltage	See Note 5		1.5		5	V
ΔIV <sub>OD</sub> I	Change in magnitude of differential output voltage§	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			+3 –1	٧
ΔIVOCI	Change in magnitude of common-modeoutput voltage§	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			±0.2	V
la	Output current	Output disabled,	V <sub>O</sub> = 12 V			1	mA
Ю	Output current	See Note 6	V <sub>O</sub> = -7 V			-0.8	ША
ΙΗ	High-level input current	V <sub>I</sub> = 2.4 V				20	μΑ
I <sub>Ι</sub> L	Low-level input current	V <sub>I</sub> = 0.4 V				-400	μΑ
		V <sub>O</sub> = -7 V				-250	
	Short circuit output current	V <sub>O</sub> = 0				-150	mA
los	Short-circuit output current	$V_O = V_{CC}$				250	ША
		V <sub>O</sub> = 12 V				250	
loo	Supply current (total package)	No load	Outputs enabled		42	70	mA
Icc	Supply current (total package)	Outputs disabled			26	35	IIIA

<sup>†</sup> The power-off measurement in ANSI Standard TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs. ‡ All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^{\circ}\text{C}$ .

NOTES: 5. See ANSI Standard TIA/EIA-485-A, Figure 3.5, Test Termination Measurement 2.

## switching characteristics, $V_{CC}$ = 5 V, $R_L$ = 110 $\Omega$ , $T_A$ = 25°C (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		TYP	MAX	UNIT
t <sub>d</sub> (OD)	Differential-output delay time	$R_L = 54 \Omega$ ,	See Figure 3		15	22	ns
t <sub>t</sub> (OD)	Differential-output transition time	$R_L = 54 \Omega$ ,	See Figure 3		20	30	ns
<sup>t</sup> PZH	Output enable time to high level	See Figure 4			85	120	ns
t <sub>PZL</sub>	Output enable time to low level	See Figure 5			40	60	ns
<sup>t</sup> PHZ	Output disable time from high level	See Figure 4			150	250	ns
tPLZ	Output disable time from low level	See Figure 5			20	30	ns

<sup>§ ∆|</sup>V<sub>OD</sub>| and ∆|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

 $<sup>\</sup>P$  The minimum  $V_{\mbox{OD2}}$  with a 100- $\Omega$  load is either 1/2  $V_{\mbox{OD1}}$  or 2 V, whichever is greater.

<sup>6.</sup> This applies for both power on and off; refer to ANSI Standard TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

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#### **SYMBOL EQUIVALENTS**

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V <sub>oa</sub> , V <sub>ob</sub>	V <sub>oa</sub> , V <sub>ob</sub>
IV <sub>OD1</sub> I	V <sub>o</sub>	Vo
V <sub>OD2</sub>	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
l <sub>A</sub> OD3l		V <sub>t</sub> (test termination measurement 2)
Δ V <sub>OD</sub>	$   V_t  -  \overline{V}_t   $	$   V_t -  \overline{V}_t   $
Voc	V <sub>os</sub>	V <sub>os</sub>
Δ VOC	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	I <sub>sa</sub>  ,  I <sub>sb</sub>	
lo	$ I_{xa} ,  I_{xb} $	l <sub>ia</sub> , l <sub>ib</sub>

#### **RECEIVER SECTION**

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST C	TEST CONDITIONS			MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	V <sub>O</sub> = 2.7 V,	$I_0 = -0.4 \text{ mA}$			0.2	V
$V_{IT-}$	Negative-going input threshold voltage	$V_0 = 0.5 V$ ,	I <sub>O</sub> = 8 mA	-0.2‡			V
$V_{hys}$	Input hysteresis voltage (V <sub>IT+</sub> – V <sub>IT</sub> –)				50		mV
٧ıK	Enable Input clamp voltage	I <sub>I</sub> = -18 mA				-1.5	V
Vон	High-level output voltage	V <sub>ID</sub> = 200 mV, See Figure 2	$I_{OH} = -400  \mu A$ ,	2.7			٧
VOL	Low-level output voltage	V <sub>ID</sub> = -200 mV, See Figure 2	I <sub>OL</sub> = 8 mA,			0.45	٧
loz	High-impedance-state output current	V <sub>O</sub> = 0.4 V to 2.4 V				±20	μΑ
Ī	Line input current	Other input = 0 V,	V <sub>I</sub> = 12 V			1	mA
ΙΙ		See Note 7	V <sub>I</sub> = −7 V			-0.8	l IIIA
lн	High-level enable input current	V <sub>IH</sub> = 2.7 V				20	μΑ
Ι <sub>Ι</sub> L	Low-level enable input current	V <sub>IL</sub> = 0.4 V				-100	μΑ
rĮ	Input resistance	V <sub>I</sub> = 12 V		12			kΩ
los	Short-circuit output current			-15		-85	mA
1	Cumply ourrent (total popleage)	Nolood	Outputs enabled		42	55	A
ICC	Supply current (total package)	No load	Outputs disabled		26	35	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

NOTE 7: This applies for both power on and power off. Refer to EIA Standard TIA/EIA-485-A for exact conditions.



<sup>&</sup>lt;sup>‡</sup> The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

# switching characteristics, $V_{CC}$ = 5 V, $C_L$ = 15 pF, $T_A$ = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	V <sub>ID</sub> = 0 to 3 V, See Figure 6		21	35	ns
tPHL	Propagation delay time, high- to low-level output	VID = 0 to 3 V, See Figure 6		23	35	115
<sup>t</sup> PZH	Output enable time to high level	See Figure 7		10	20	no
tPZL	Output enable time to low level	See Figure 7		12	20	ns
<sup>t</sup> PHZ	Output disable time from high level	See Figure 7		20	35	no
tPLZ	Output disable time from low level	See Figure /		17	25	ns

#### PARAMETER MEASUREMENT INFORMATION

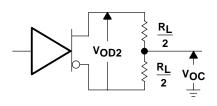


Figure 1. Driver V<sub>OD</sub> and V<sub>OC</sub>

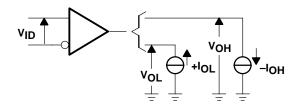
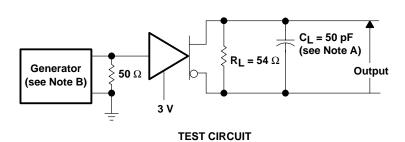
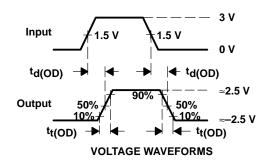


Figure 2. Receiver VOH and VOL



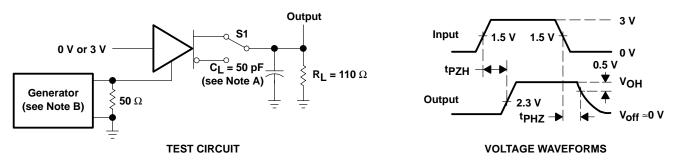


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns

Figure 3. Driver Test Circuit and Voltage Waveforms

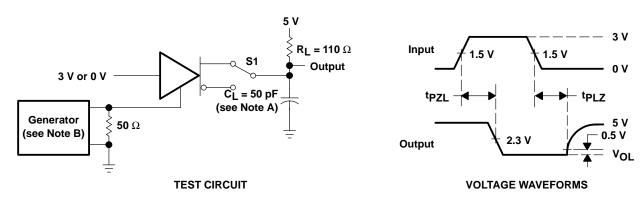
#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  8 ns

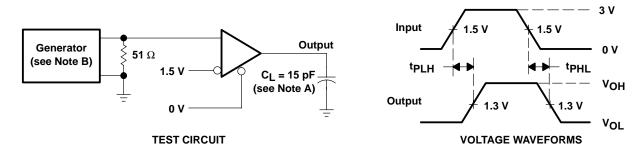
Figure 4. Driver Test Circuit and Voltage Waveforms



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{f} \leq$  6 ns,  $Z_{O} = 50 \Omega$ .

Figure 5. Driver Test Circuit and Voltage Waveforms



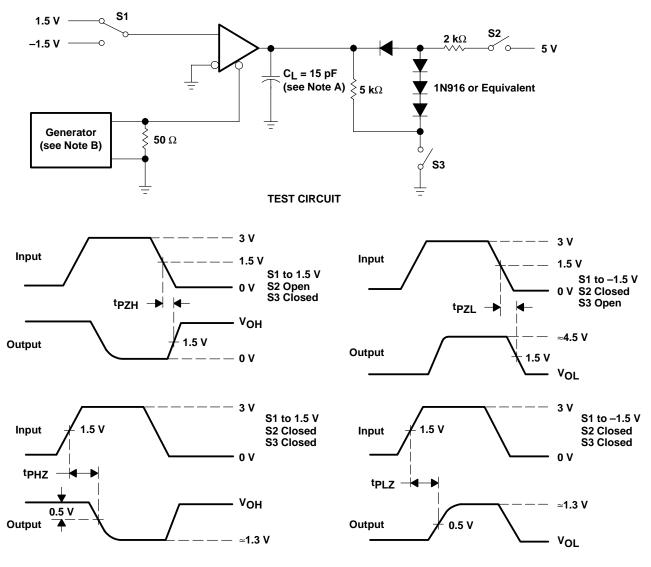
NOTES: A. CL includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns

Figure 6. Receiver Test Circuit and Voltage Waveforms



#### PARAMETER MEASUREMENT INFORMATION



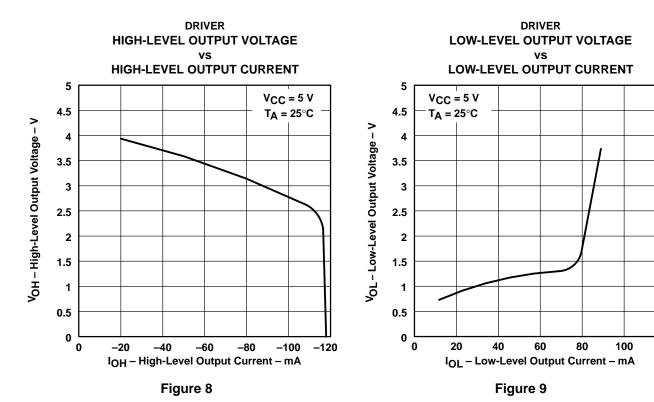
#### **VOLTAGE WAVEFORMS**

NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O = 50 \Omega$ .

Figure 7. Receiver Test Circuit and Voltage Waveforms

#### **TYPICAL CHARACTERISTICS**



# DRIVER DIFFERENTIAL OUTPUT VOLTAGE

120

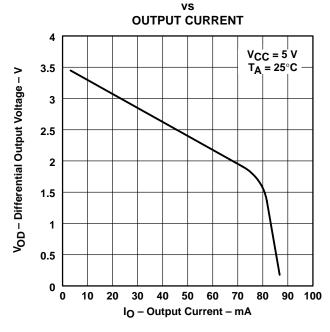


Figure 10



#### TYPICAL CHARACTERISTICS

#### **RECEIVER** HIGH-LEVEL OUTPUT VOLTAGE HIGH-LEVEL OUTPUT CURRENT 5 $V_{1D} = 0.2 V$ T<sub>A</sub> = 25°C 4.5 VoH - High-Level Output Voltage - V 4 3.5 3 2.5 $V_{CC} = 5.25 \text{ V}$ 2 **V<sub>CC</sub>** = 5 **V** 1.5 V<sub>CC</sub> = 4.75 V 1 0.5 0 -10 -15 -20 -25 -30 -35 -40 -45 -50

Figure 11

IOH - High-Level Output Current - mA

**RECEIVER** 

**LOW-LEVEL OUTPUT VOLTAGE** 

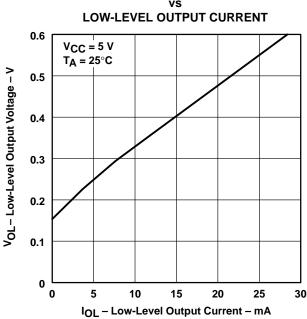
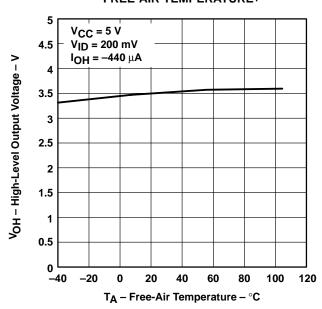


Figure 13

# RECEIVER HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE†



<sup>†</sup>Only the 0°C to 70°C portion of the curve applies to the SN75176B.

Figure 12

# RECEIVER LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

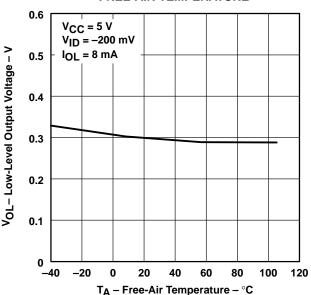
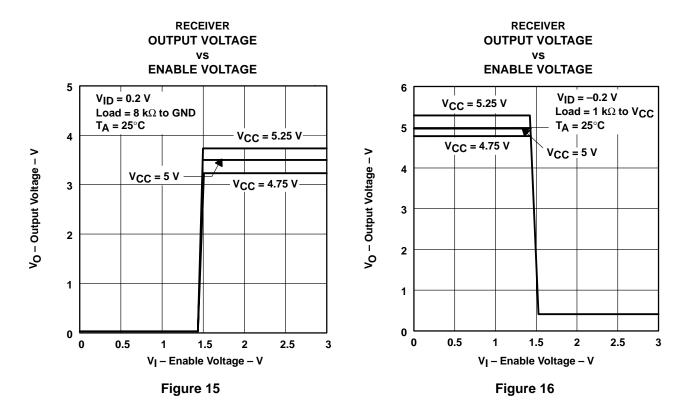
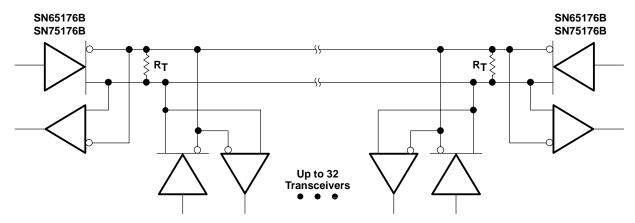


Figure 14

#### **TYPICAL CHARACTERISTICS**



#### **APPLICATION INFORMATION**



NOTE A: The line should be terminated at both ends in its characteristic impedance (R<sub>T</sub> = Z<sub>O</sub>). Stub lengths off the main line should be kept as short as possible.

Figure 17. Typical Application Circuit









#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN65176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $<sup>^{(1)}</sup>$  The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



#### PACKAGE OPTION ADDENDUM

24-Oct-2006

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

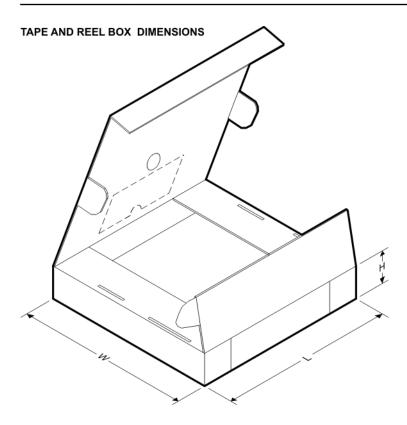
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75176BPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1





\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65176BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75176BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75176BPSR	SO	PS	8	2000	346.0	346.0	33.0

# P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE PACKAGE



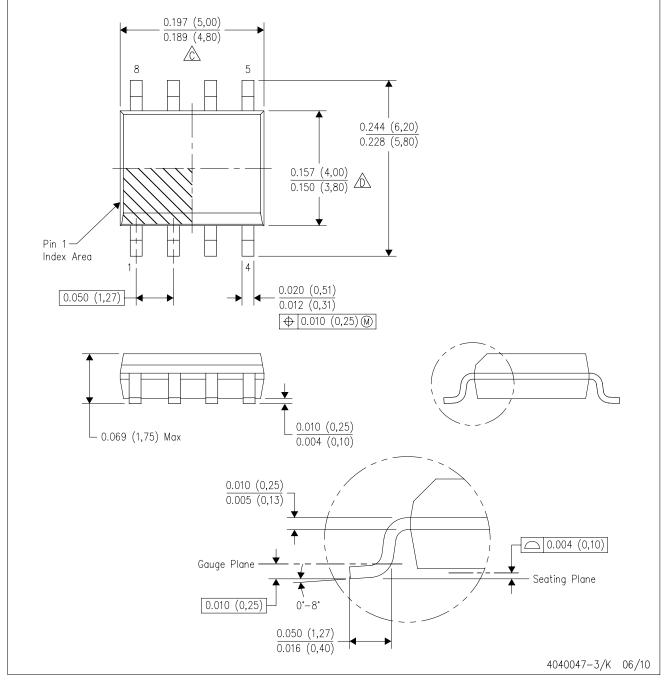
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



# D (R-PDSO-G8)

#### PLASTIC SMALL-OUTLINE PACKAGE



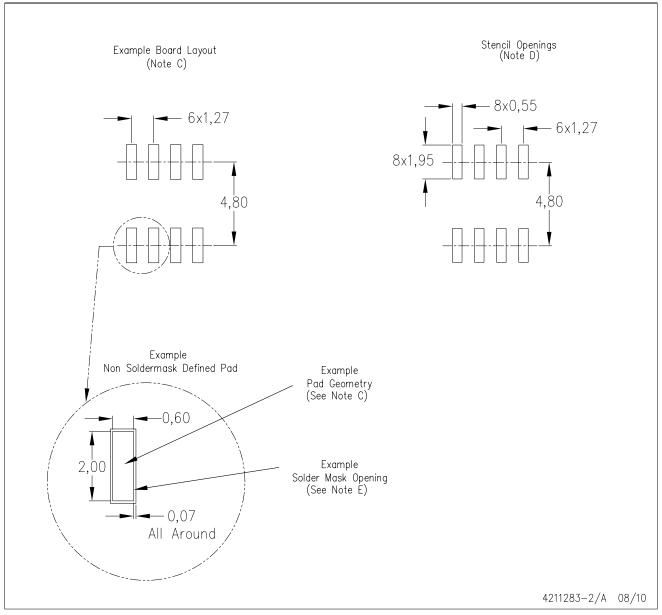
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



# D (R-PDSO-G8)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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